

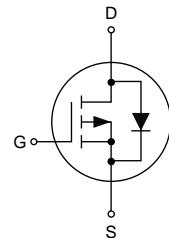
P-Channel Enhancement Mode MOSFET

1. Product Information

Features

- Advanced Trench Technology
- Excellent $R_{DS(ON)}$
- Low Gate Charge

Schematic Diagram



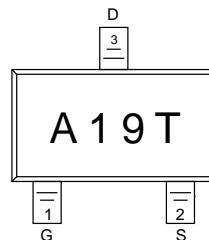
Applications

- PWM Applications
- Load Switch

Quick reference

- $V_{DS} = -30 \text{ V}$
- $I_D = -4.0 \text{ A}$
- $P_D = 0.72 \text{ W}$
- $R_{DS(ON)} \leq 70 \text{ m}\Omega @ V_{GS}=10 \text{ V}$ (Type: 55 m Ω)
- $R_{DS(ON)} \leq 90 \text{ m}\Omega @ V_{GS}=4.5 \text{ V}$ (Type: 75 m Ω)

Pin Assignment



SOT23-3L

Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape Width	Quantity(pcs)
KJ3401B	SOT23-3L	A19T	7"	8 mm	3000

2. Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Values	Unit
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 12	V
I_D	Continuous Drain Current, $T_A=25^\circ\text{C}$ ¹	-4.0	A
	Continuous Drain Current, $T_A=70^\circ\text{C}$ ¹	-3.2	A
I_{DM}	Pulsed Drain Current ²	-16	A
P_D	Power Dissipation, $T_A=25^\circ\text{C}$ ¹	0.72	W
	Power Dissipation, $T_A=70^\circ\text{C}$ ¹	0.46	W
I_S	Continuous Source Current (diode conduction) ¹	-0.6	A
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55~150	°C
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient ¹	125	°C/W
$R_{\theta JC}$	Thermal Resistance from Junction to Case	80	°C/W

3. Electrical Characteristics ($T_A=25^\circ C$, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
OFF Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{ V}$, $I_D=-250\text{ }\mu\text{A}$	-30		-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{ V}$, $V_{GS}=0\text{ V}$	-	-	-1	μA
I_{GS}	Gate-Source Leakage	$V_{DS}=0\text{ V}$, $V_{GS}=\pm 12\text{ V}$	-	-	± 100	nA
ON Characteristics						
$V_{GS(th)}$	Gate-Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\text{ }\mu\text{A}$	-0.5	-0.85	-1.3	V
$R_{DS(ON)}$	Drain-Source On-Resistance ³	$V_{GS}=-4.5\text{ V}$, $I_D=-4\text{ A}$	-	55	70	$\text{m}\Omega$
		$V_{GS}=-2.5\text{ V}$, $I_D=-3\text{ A}$	-	75	90	
g_{FS}	Forward transconductance	$V_{DS}=-5\text{ V}$, $I_D=-4\text{ A}$	-	9	-	S
Dynamic Characteristics ⁴						
C_{iss}	Input Capacitance	$V_{DS}=-15\text{ V}$, $V_{GS}=0\text{ V}$, $f=1.0\text{ MHz}$	-	676	-	pF
C_{oss}	Output Capacitance		-	60	-	
C_{rss}	Reverse Transfer Capacitance		-	51	-	
Switching Characteristics ⁴						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=-15\text{ V}$, $V_{GS}=-10\text{ V}$, $R_G=6\text{ }\Omega$, $R_L=3.6\text{ }\Omega$, $I_D=-3\text{ A}$	-	8	-	ns
t_r	Turn-on Rise Time		-	5	-	
$t_{d(off)}$	Turn-off Delay Time		-	26	-	
t_f	Turn-off Fall Time		-	11	-	
Q_g	Total Gate Charge	$V_{DS}=-8\text{ V}$, $V_{GS}=-4.5\text{ V}$, $I_D=-3\text{ A}$	-	8.2	-	nC
Q_{gs}	Gate-Source Charge		-	1.8	-	
Q_{gd}	Gate-Drain Charge		-	2.0	-	
Drain-Source Diode Characteristics ⁴						
V_{SD}	Diode Forward Voltage	$V_{GS}=0\text{ V}$, $I_S=-1\text{ A}$	-	-0.75	-1.2	V

Notes:

1. Surface mounted on 1" x 1" FR4 board.
2. Pulse width limited by maximum junction temperature.
3. Pulse test: Pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
4. Guaranteed by design, not subject to production testing.

4. Typical Characteristics

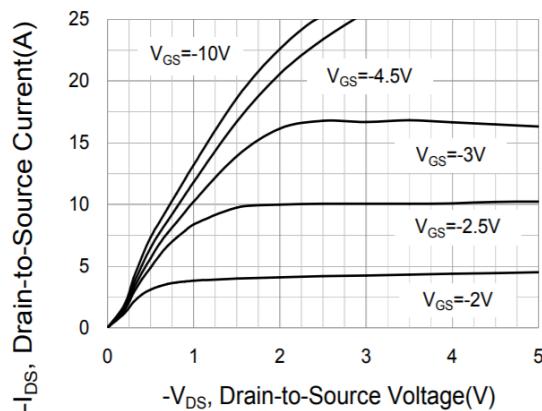


Figure 1. Output Characteristics

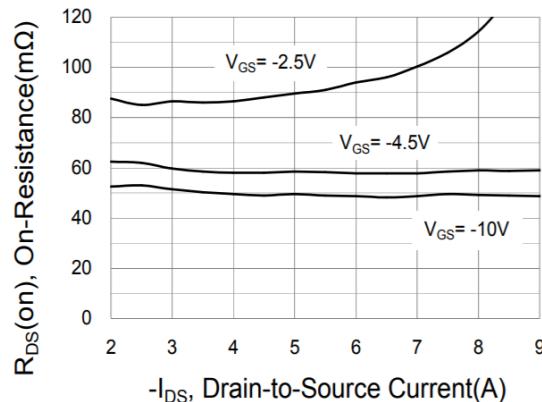


Figure 2. On-Resistance vs. Drain Current

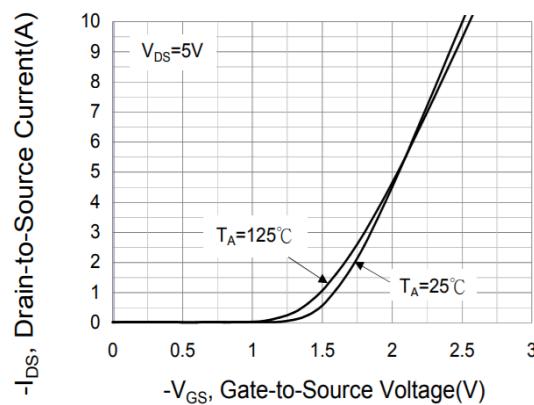


Figure 3. Transfer Characteristic

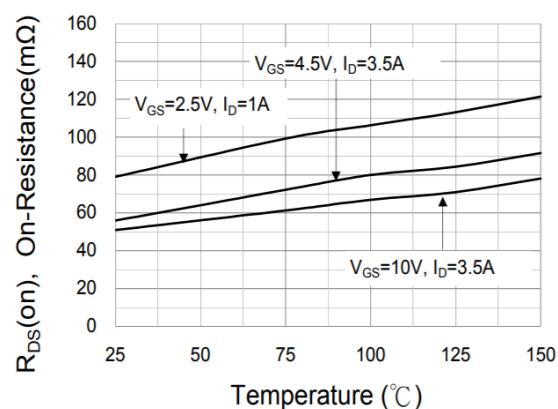


Figure 4. On-Resistance vs. Junction Temperature

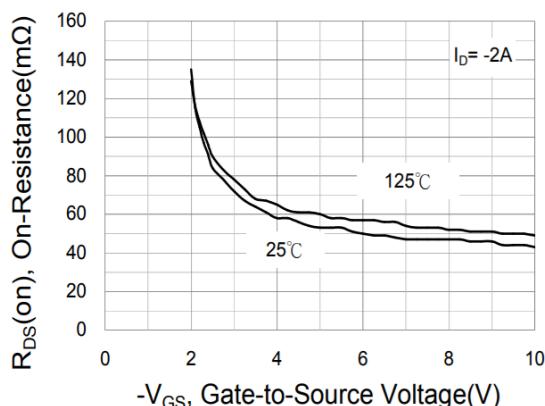


Figure 5 On-Resistance vs. V_{GS}

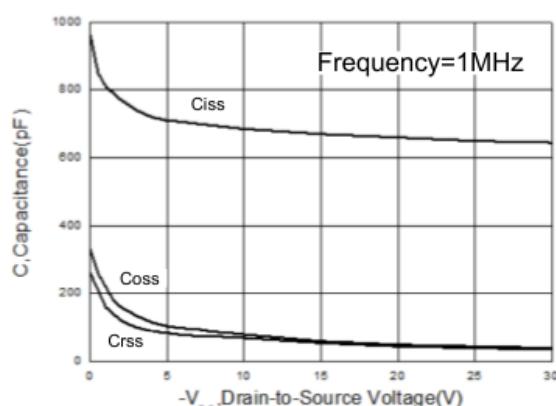


Figure 6 Capacitance Characteristic

4. Typical Characteristics (cont.)

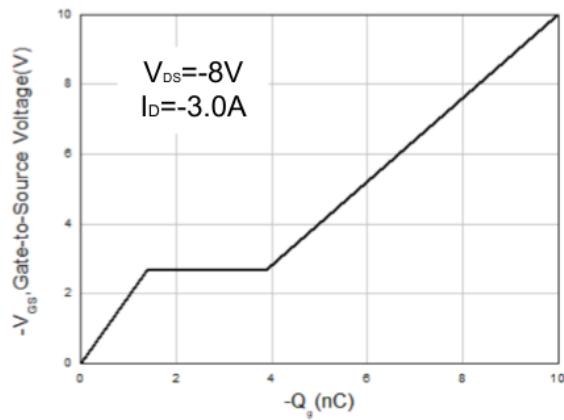


Figure. 7 Gate-Charge Characteristic

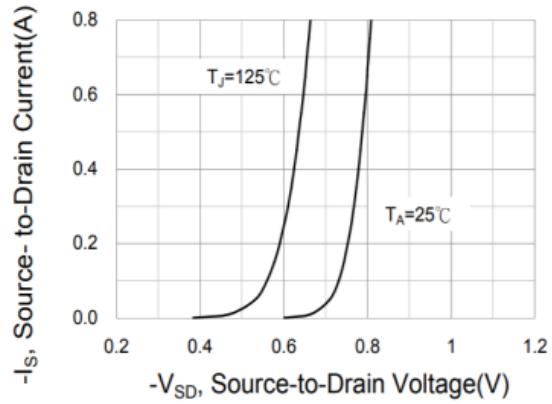
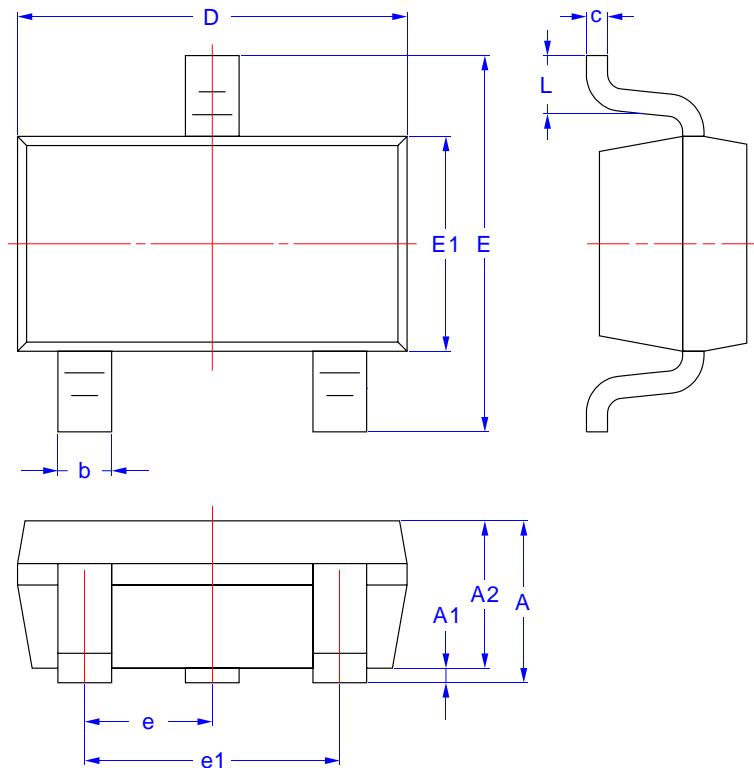


Figure. 8 Body Diode Characteristic

5. Package Mechanical Data

SOT23-3L Package



Symbol	Dimensions in Millimeters	
	MIN	MAX
A	1.00	1.45
A1	0.00	0.15
A2	1.00	1.30
D	2.70	3.10
E	2.60	3.00
E1	1.50	1.70
c	0.08	0.25
b	0.30	0.50
e	0.95 BSC	
e1	1.90 BSC	
L	0.30	0.60